

AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A bonding structure with a buffer layer, comprising:
  - a first substrate;
  - a plurality of metal pads on a surface of said first substrate;
  - a protection layer covering on said surface of said first substrate;
  - a first adhesive metal layer being formed on said ~~plural plurality~~ of metal pads;
  - a buffer layer being coated on said protection layer and said ~~plural of metal pads~~ first adhesive metal layer;
  - a first metal layer covering said buffer layer, said first metal layer being independently distributed on surface areas of said buffer layer opposite to said protection layer and said first adhesive metal layer;
  - a second substrate having a plurality of electrodes thereon; and
  - a bonding layer, said bonding layer and said ~~plural plurality~~ of electrodes being independently distributed on said second substrate;

wherein said first metal layer, said ~~plural plurality~~ of electrodes and said bonding layer are bonded directly to complete said bonding structure.
2. (Currently Amended) The bonding structure as claimed in claim 1, wherein said bonding is said first metal layer, said plurality of electrodes and said bonding layer are bonded by direct bonding.
3. (Currently Amended) The bonding structure as claimed in claim 1, wherein said

plurality of electrodes on said second substrate are respectively aligned to said plurality of metal pads on said surface of said first substrate.

4. (Currently Amended) The bonding structure as claimed in claim 1, wherein said buffer layer coated on said first adhesive metal layer over said plurality of metal pads and said buffer layer on said protection layer are independently distributed.

5. (Currently Amended) The bonding structure as claimed in claim 1, wherein said buffer layer coated on said first adhesive metal layer over said plurality of metal pads and said buffer layer on said protection layer are connected.

6. (Currently Amended) The bonding structure as claimed in claim 1, wherein said first substrate is a ~~silicone~~ silicon substrate.

7. (Currently Amended) The bonding structure as claimed in claim 1, wherein said second substrate is one of glass substrate, polymer substrate, ~~silicone~~ silicon substrate or ceramic substrate.

8. (Original) The bonding structure as claimed in claim 1, wherein the material for said first metal layer is chosen from one of gold, aluminum or copper.

9. (Original) The bonding structure as claimed in claim 1, wherein the material for said buffer layer is polymer.

10. (Original) The bonding structure as claimed in claim 1, wherein under-fill is further applied between said first substrate and said second substrate to increase the reliability of said bonding structure.

11-13. (Cancelled).

14. (Original) The bonding structure as claimed in claim 3, wherein a second metal layer is formed on said bonding layer located on said second substrate.
15. (Original) The bonding structure as claimed in claim 3, wherein a second metal layer is formed on said plurality of electrodes and on said bonding layer located on said second substrate.
16. (Original) The bonding structure as claimed in claim 4, wherein a second metal layer is formed on said bonding layer located on said second substrate.
17. (Currently Amended) The bonding structure as claimed in claim 4, wherein a second metal layer is formed on said ~~plural~~ of electrodes and on said bonding layer located on said second substrate.
- 18-29. (Cancelled).